



CNY17-1, CNY17-2, CNY17-3, CNY17-4 CNY17F-1, CNY17F-2, CNY17F-3, CNY17F-4 DC Input 6-Pin DMC-Isolator® Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Various CTR selection available
- DC input with transistor output
- Operating Temperature range - 55 °C to 110 °C
- External Creepage $\geq 7.4\text{mm}$
- Distance Through Isolation $\geq 0.4\text{mm}$
- Spatial Distance $\geq 7.5\text{mm}$ (S/SL Type)
- Spatial Distance $\geq 8.0\text{mm}$ (M Type)
- RoHS and REACH compliance
- Halogen compliance(Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL - UL1577 (E364000)
 - ✓ VDE - EN60747-5-5(VDE0884-5)
 - ✓ CQC – GB4943.1, GB8898 (14001105802)
 - ✓ IEC62368 (FI/41119)

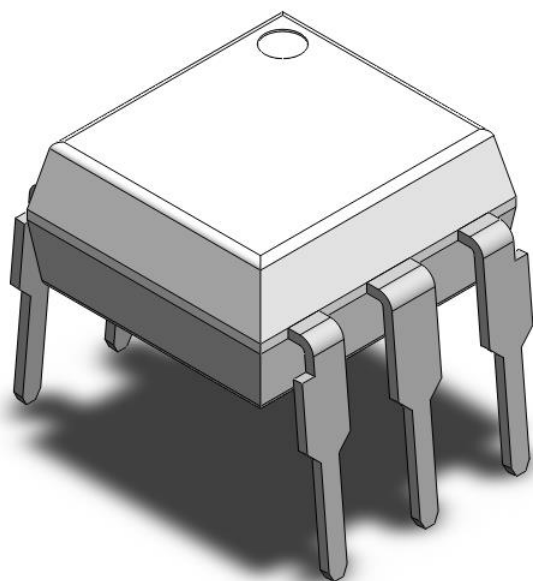
Description

The CNY17 and CNY17F series consists of a photo transistor optically coupled to an Infrared-emitting diode in a 6-lead DIP DMC-Isolator® package with different lead forming options.

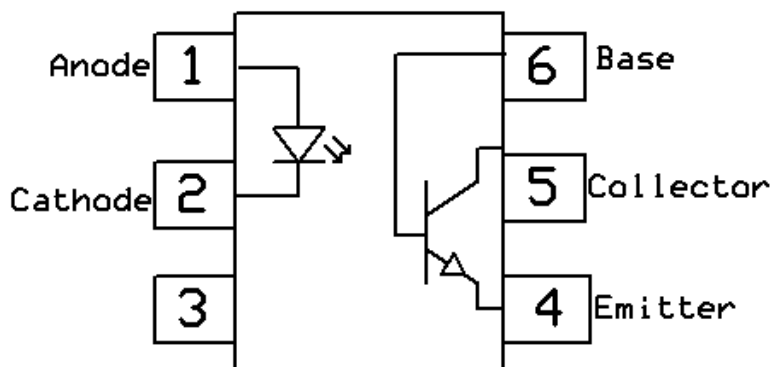
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic



Note: CNY17F without Base Connection

Note: Different lead forming options available. See package dimension.



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CNY17F-1, CNY17F-2, CNY17F-3, CNY17F-4
DC Input 6-Pin DMC-Isolator®
Phototransistor Optocoupler

Absolute Maximum Ratings $T_A = 25^{\circ}\text{C}$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
V _{ISO}	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	V _{RMS}	
T _{OPR}	Operating temperature	-55 ~ +110	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature (For 10 seconds)	260	°C	
Emitter				
I _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (≤1μs P.W,300pps)	1	A	
V _R	Reverse voltage	6	V	
P _D	Power dissipation	100	mW	
Detector				
P _D	Power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
B _{VCBO}	Collector-Base Breakdown Voltage	80	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	7	V	
B _{VEBO}	Emitter-Base Breakdown Voltage	7	V	



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Electrical Characteristics $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	$I_F = 10\text{mA}$		1.24	1.4	V	
I_R	Reverse Current	$V_R = 6\text{V}$	-	-	5	μA	
C_{IN}	Input Capacitance	$f = 1\text{MHz}$	-	20	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$B_{V_{CEO}}$	Collector-Emitter Breakdown	$I_C = 0.1\text{mA}$	80	-	-	V	
$B_{V_{ECO}}$	Emitter-Collector Breakdown	$I_E = 0.1\text{mA}$	7	-	-	V	
$B_{V_{CBO}}$	Collector-Base Breakdown	CNY17-1/2/3/4 $I_C = 0.1\text{mA}$	80	-	-	V	
$B_{V_{EBO}}$	Emitter-Base Breakdown		$I_E = 0.1\text{mA}$	7	-	-	V
I_{CEO}	Collector-Emitter Dark Current	$V_{CE} = 10\text{V}, I_F = 0\text{mA}$	-	-	50	nA	
I_{CBO}	Collector-Base Dark Current	CNY17-1/2/3/4 $V_{CB} = 10\text{V}, I_F = 0\text{mA}$	-	-	20	nA	



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Phototransistor Optocoupler

Electrical Characteristics $T_A = 25^\circ\text{C}$ (unless otherwise specified)

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes	
CTR	Current Transfer Ratio	$I_F = 10\text{mA}, V_{CE} = 5\text{V}$	CNY17-1,CNY17F-1	40	-	80	%	
			CNY17-2,CNY17F-2	63	-	125		
			CNY17-3,CNY17F-3	100	-	200		
			CNY17-4,CNY17F-4	160	-	320		
	Current Transfer Ratio	$I_F = 1\text{mA}, V_{CE} = 5\text{V}$	CNY17-1,CNY17F-1	13	-	-		
			CNY17-2,CNY17F-2	22	-	-		
			CNY17-3,CNY17F-3	34	-	-		
			CNY17-4,CNY17F-4	56	-	-		
$V_{CE(SAT)}$	Collector- Emitter Saturation Voltage	$I_F = 10\text{mA}, I_C = 2.5\text{mA}$	-	-	0.3	V		
R_{IO}	Isolation Resistance	$V_{IO} = 500\text{V}_{DC}$	1×10^{11}	-	-	Ω		
C_{IO}	Isolation Capacitance	$f = 1\text{MHz}$	-	0.25	-	pF		

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
T_{ON}	Turn On Time	$I_C = 2\text{mA}, V_{CC} = 10\text{V}, R_L = 100\Omega$	-	4.3	11.5	μs	
t_r	Rise Time		-	9.8	9.8		
T_{OFF}	Turn Off Time		-	3.9	11.5	μs	
t_f	Fall Time		-	6.9	9.8		



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Typical Characteristic Curves $T_A = 25^\circ\text{C}$, unless otherwise specified (Continued)

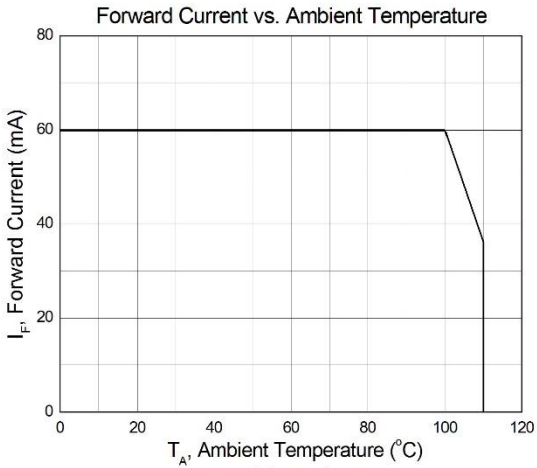


Figure 1

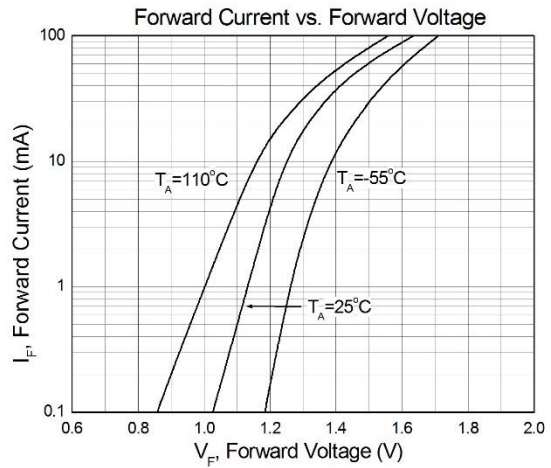


Figure 2

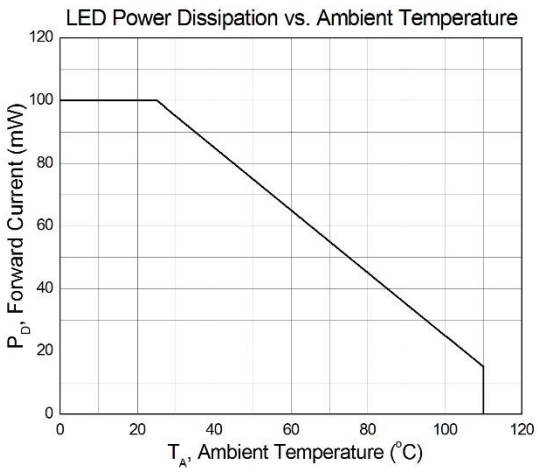


Figure 3

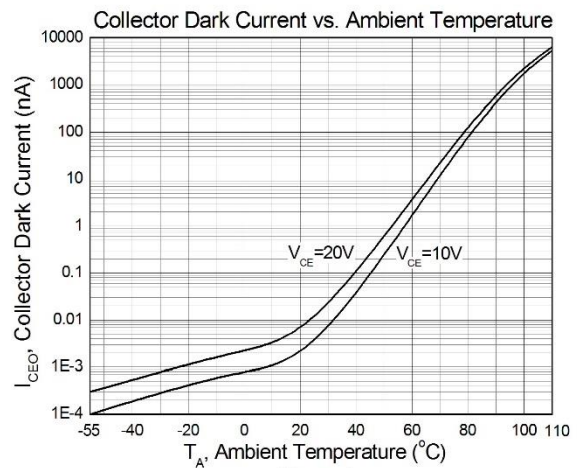


Figure 4

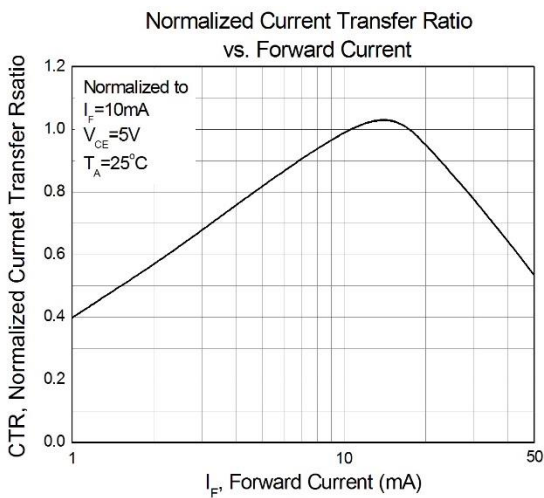


Figure 5

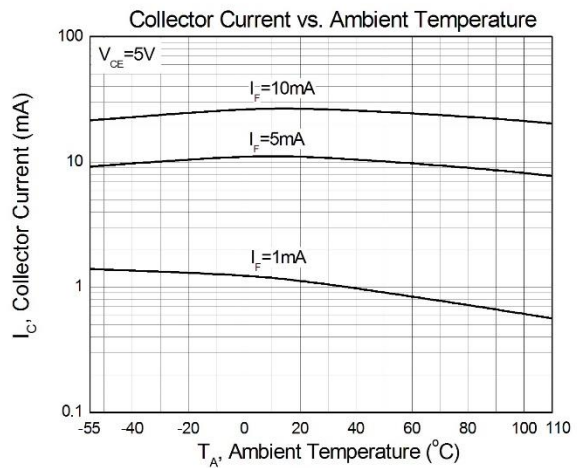


Figure 6



CNY17-1, CNY17-2, CNY17-3, CNY17-4 CNY17F-1, CNY17F-2, CNY17F-3, CNY17F-4 DC Input 6-Pin DMC-Isolator® Phototransistor Optocoupler

Typical Characteristic Curves $T_A = 25^\circ\text{C}$, unless otherwise specified (Continued)

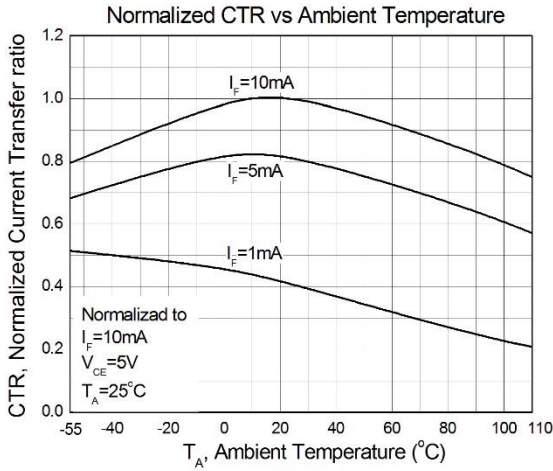


Figure 7

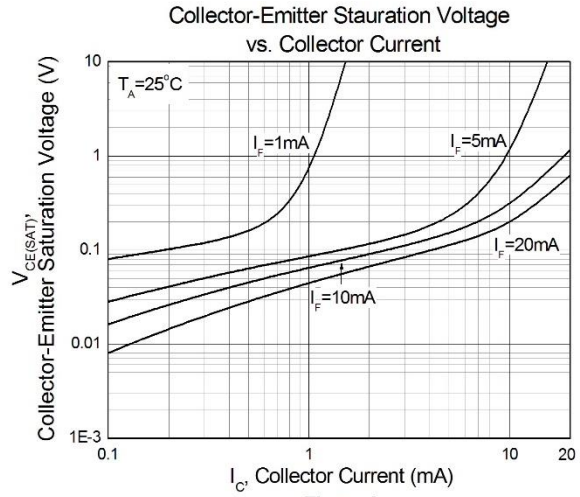


Figure 8

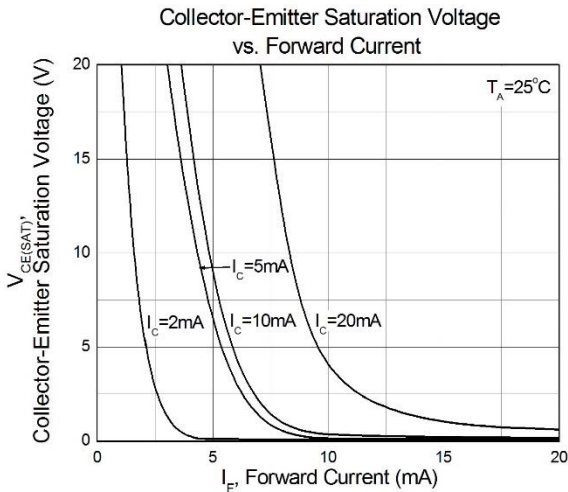


Figure 9

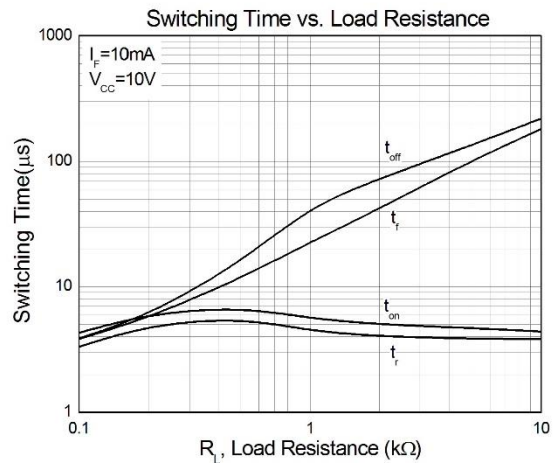


Figure 10

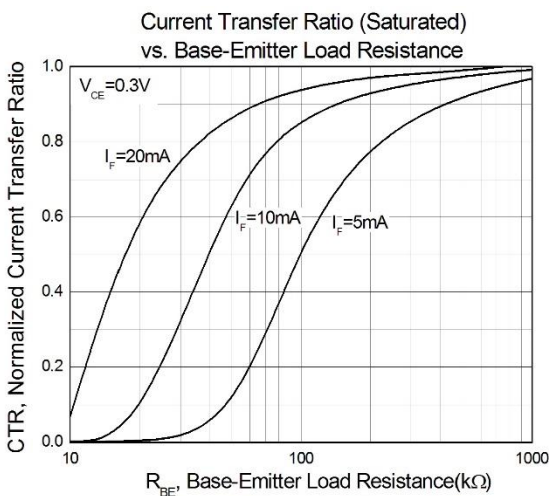


Figure 11 (For CNY17 Series Only)

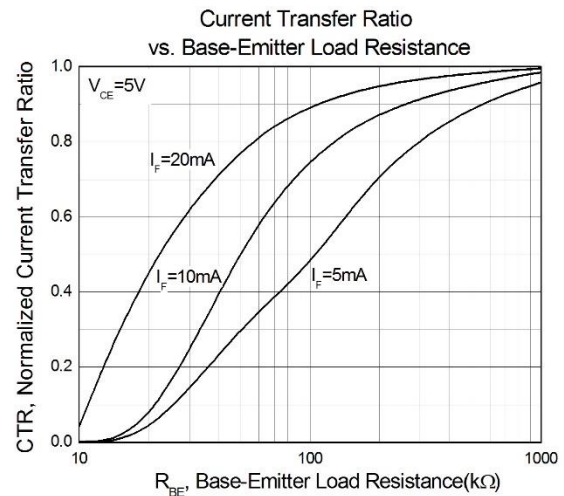
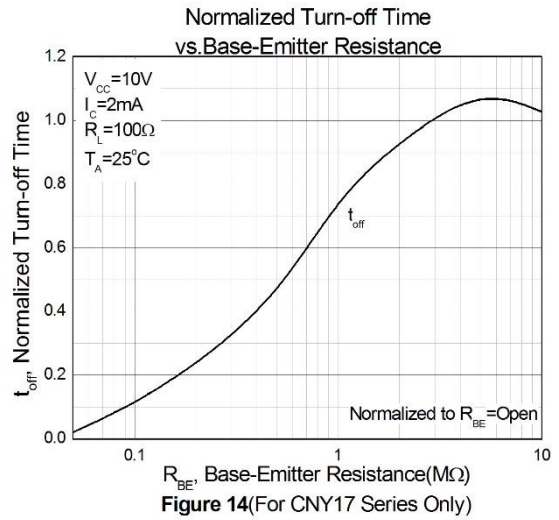
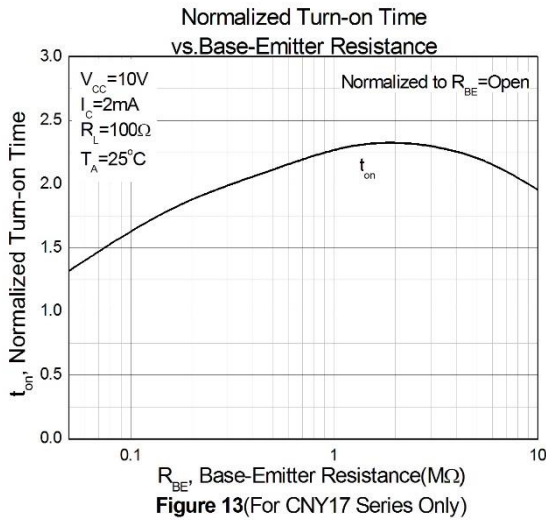


Figure 12 (For CNY17 Series Only)



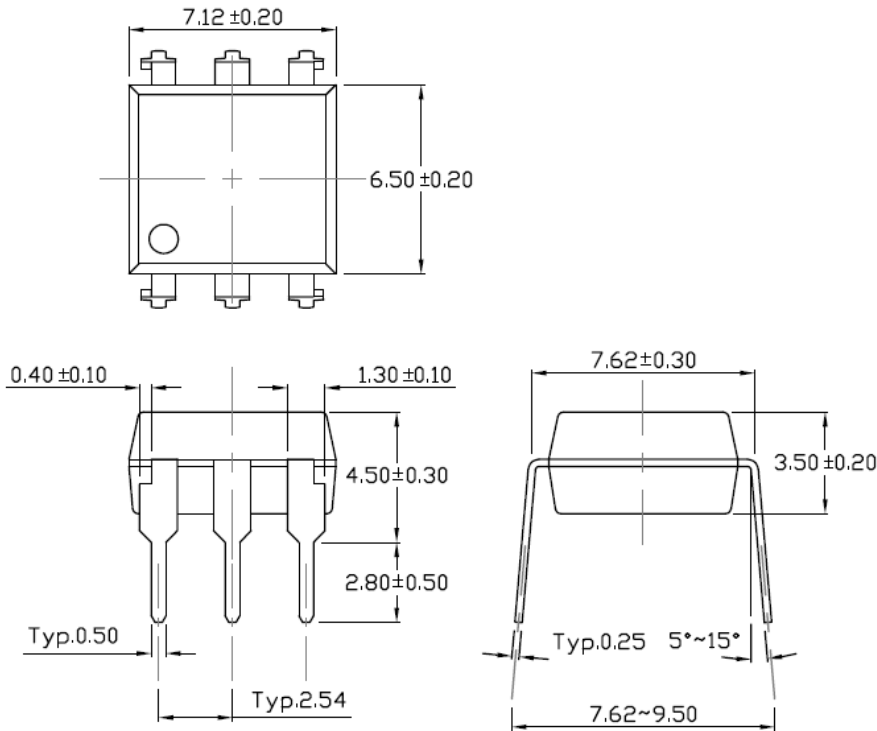
Typical Characteristic Curves $T_A = 25^\circ\text{C}$, unless otherwise specified (Continued)





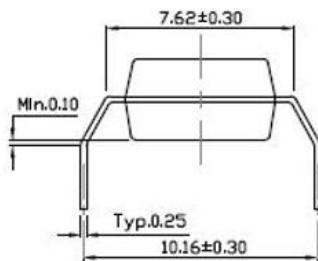
Package Dimension *Dimensions in mm unless otherwise stated*

Standard DIP – Through Hole

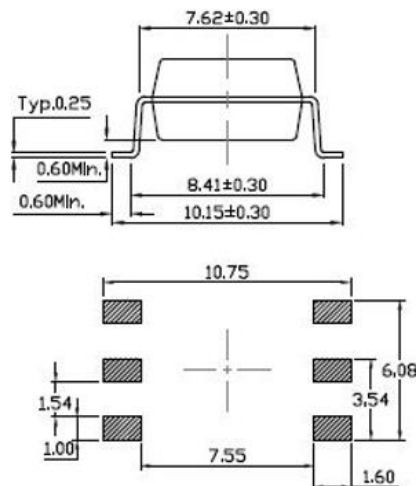


Forming Option

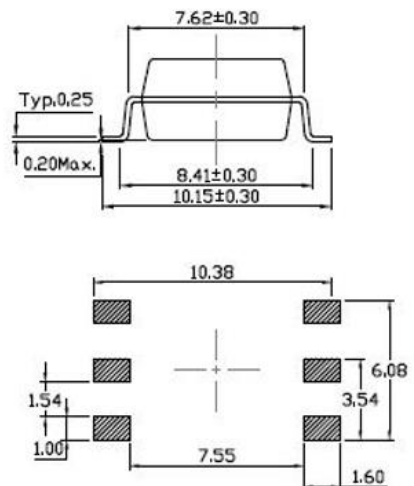
M Type



S Type



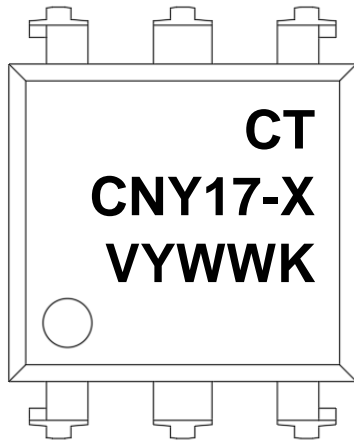
SL Type





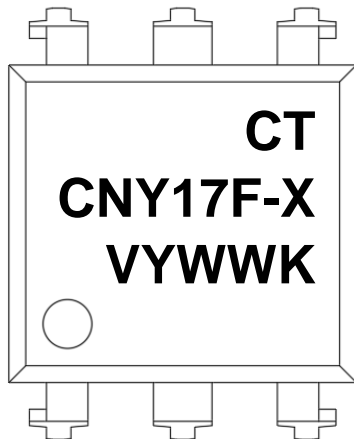
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Marking Information



Note:

CT : Denotes “CT Micro”
CNY17 : Part Number
X : CTR Rank
V : VDE Safety Mark Option (Blank or V)
Y : One Digit Year Code
WW : Two Digit Work Week
K : Manufacturing Code



Note:

CT : Denotes “CT Micro”
CNY17F : Part Number
X : CTR Rank
V : VDE Safety Mark Option
(Blank or V)
Y : One Digit Year Code
WW : Two Digit Work Week
K : Manufacturing Code



Ordering Information

CNY17-X (V)(Y)(Z)-G

- CNY17 = Part Number
- X = CTR Rank Option. (1, 2, 3 or 4)
- V = VDE Safety Mark Option (Blank or V)
- Y = Lead Form Option (Blank, S, SL or M)
- Z = Tape and Reel Option (Blank, T1 or T2)
- G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

CNY17F-X (V)(Y)(Z)-G

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- V = VDE Safety Mark Option (Blank or V)
- Y = Lead Form Option (Blank, S, SL or M)
- Z = Tape and Reel Option (Blank, T1 or T2)
- G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel

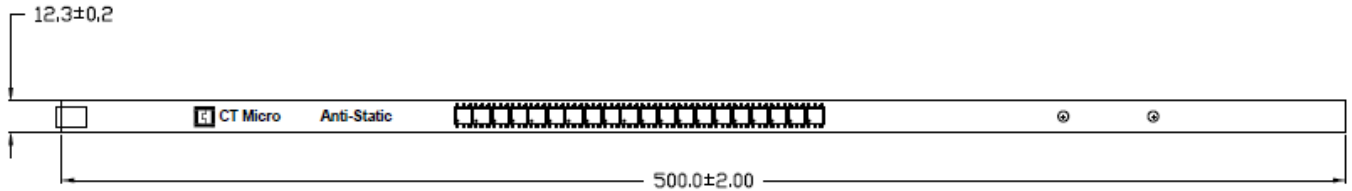


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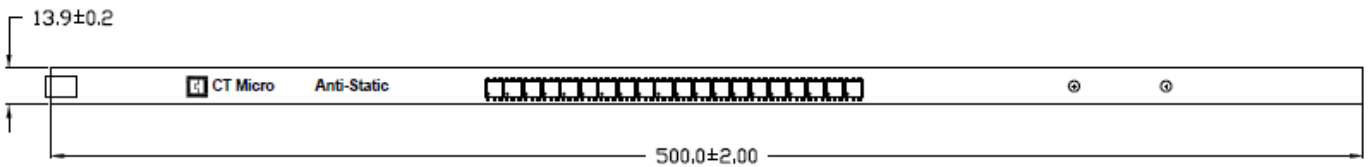
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CNY17F-1, CNY17F-2, CNY17F-3, CNY17F-4
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Carrier Specifications *Dimensions in mm unless otherwise stated*

Tube Option Standard DIP

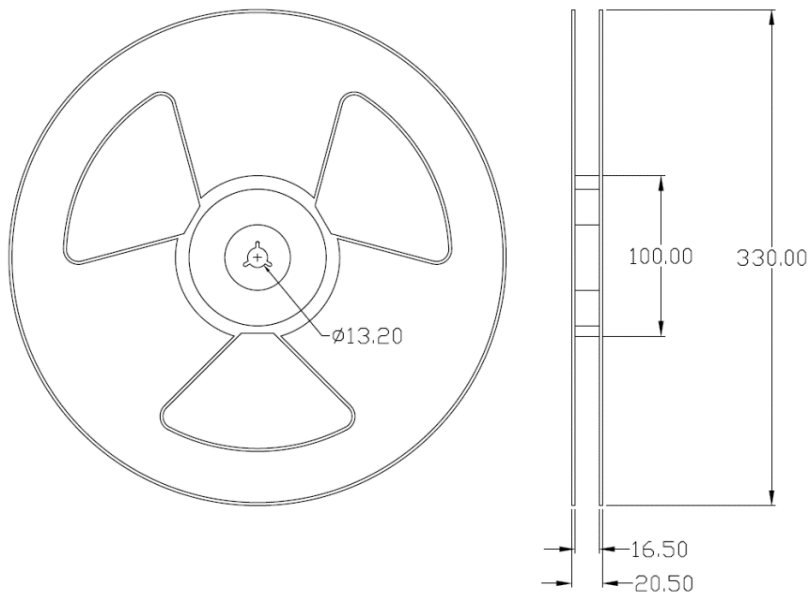


Tube Option M Type



Reel Dimension *All dimensions are in mm, unless otherwise stated*

Option S(T1/T2) & SL(T1/T2)



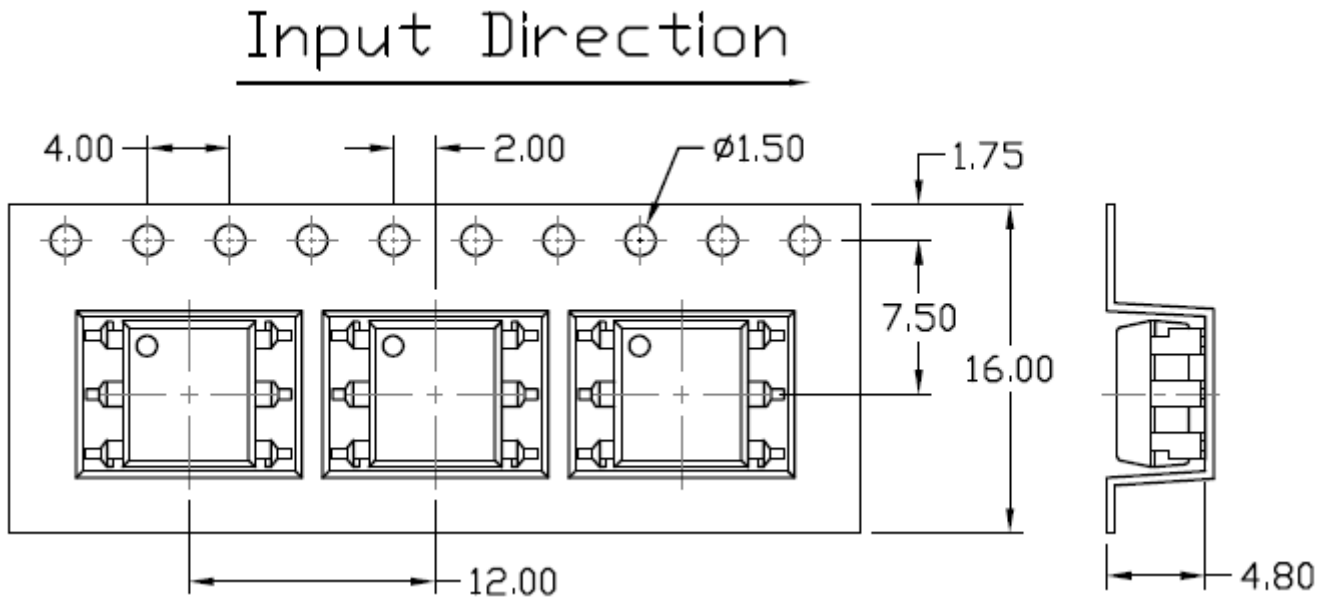


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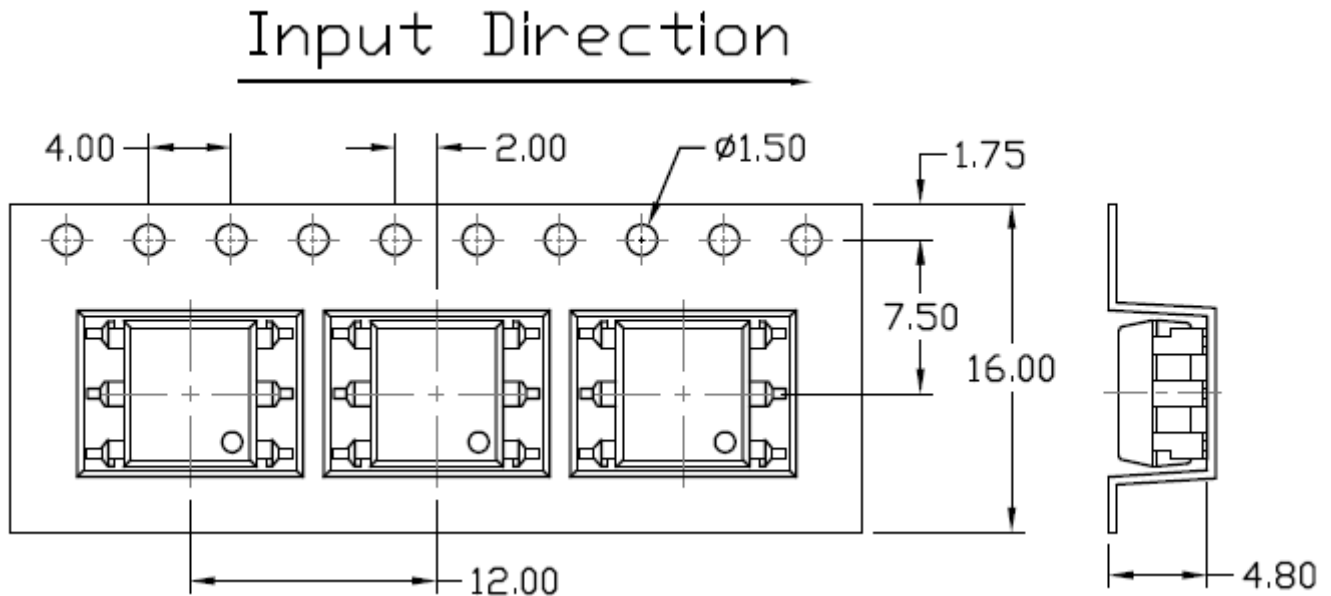
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CNY17F-1, CNY17F-2, CNY17F-3, CNY17F-4
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Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

Option S (T1) & SL (T1)



Option S (T2) & SL (T2)





Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

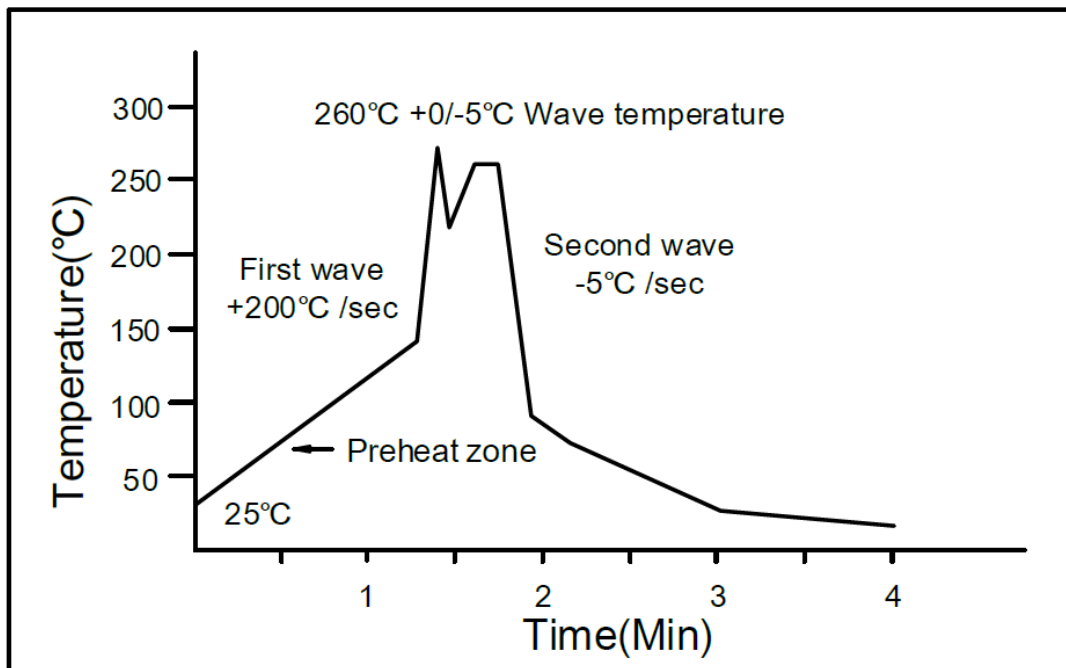
One time soldering is recommended within the condition of temperature.

Temperature: $260 \pm 5^\circ\text{C}$.

Time: 10 sec.

Preheat temperature: 25 to 140°C .

Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

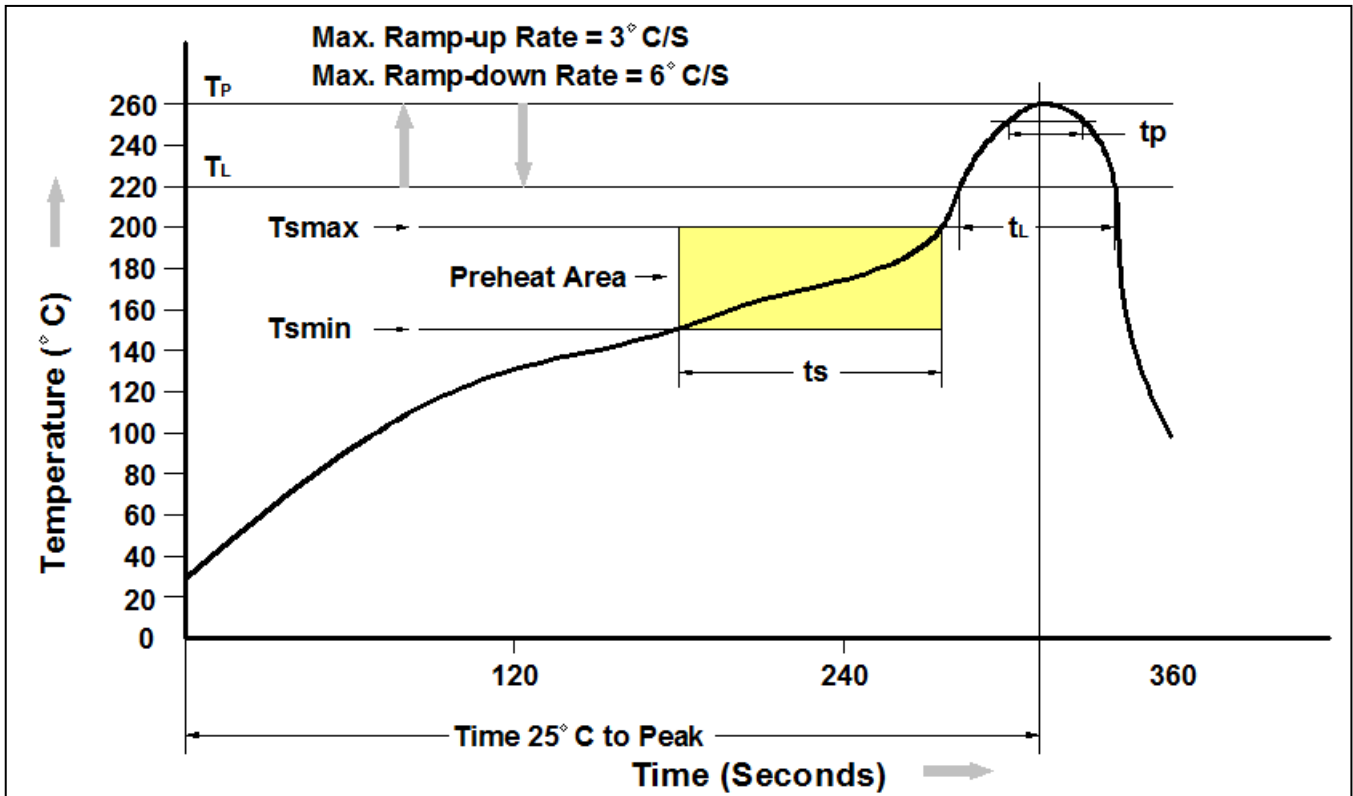
One time soldering is recommended.

Temperature: $350 \pm 10^\circ\text{C}$

Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*